

	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
	1	RE-6-1779	C.J.S	L.S.M	2020.04.07						

APPLICABLE STANDARD				
RATING	Operating Temperature Range	-55°C to 105°C (Note1)	Storage Temperature Range	-10°C to +60°C (Note3)
	Operating Humidity Range	20% to 80% (Note2)	Storage Humidity Range	40% to 70% (Note3)
	Applicable Connector	DF51K-3S-2C(###)	Current	AWG 30 : 0.5A AWG 28 : 1A AWG 22-26 : 2A
	Voltage	250V AC/DC		

SPECIFICATIONS					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT

CONSTRUCTION					
General Examination	Visually and by measuring instrument.		According to drawing.	o	o
Marking	Confirmed visually.			o	o

ELECTRICAL CHARACTERISTICS					
Contact Resistance Millivolt Level Method	20mV MAX, 1mA (DC or 1000Hz).		30 mΩ MAX.	o	-
Insulation Resistance	500 V DC.		1,000 MΩ MIN.	o	-
Voltage Proof	650 V AC for 1 min.		No flashover or breakdown.	o	-

MECHANICAL CHARACTERISTICS					
Mechanical Operation (Sn Plating)	30 times insertion and extraction.		①Contact resistance: 30mΩ MAX ②No damage, crack or looseness of parts.	o	-
Mechanical Operation (Au Plating)	50 times insertion and extraction.		①Contact resistance: 30mΩ MAX ②No damage, crack or looseness of parts.	o	-
Mating and unmating force (Sn Plating)	It takes out and inserts with a conformity connector.		①Insertion Force: 26.0N MAX ②Extraction Force : 0.75N MIN	o	-
Mating and unmating force (Au Plating)	It takes out and inserts with a conformity connector.		①Insertion Force: 17.7N MAX ②Extraction Force: 0.75N MIN	o	-
Vibration	Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction.		①No electrical discontinuity of 1 μs. ②No damage, crack or looseness of parts.	o	-
Shock	Acceleration 490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.			o	-

ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady State)	Exposed at 40 ± 2 °C , humidity 90 to 95 %, 96 h. (After leaving the room temperature for 1 to 2h.)		①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 500MΩ MIN. ③No damage, crack or looseness of parts.	o	-

Remarks Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation.				
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	DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
	J.S CHOI	J.S CHOI	S.M.LIM	T.S KANG	
	18.03.02	18.03.02	18.03.02	18.03.02	

Unless otherwise specified, refer to IEC 60512.

NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST O: APPLICABLE TEST				
HIROSE KOREA CO.,LTD.		SPECIFICATION SHEET		PART NO.
				DF51KB-3P-2DS(800)
CODE NO.(OLD) CL	DRAWING NO. ELC4-632587	CODE NO.	CL 6652-0062-6-800	

1/2

Rapid Change of Temperature	Temperature -55 °C → +105 °C Time 30min → 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.)	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts.	O	—
Dry Heat	Exposed at 105±2 °C, 96h	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts.	O	—
Cold	Exposed at -55±3 °C, 96h	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts.	O	—
Resistance To Soldering Heat	①Automatic soldering (flow) Soldered at solder temperature, 260 °C for in immersion , duration, 5 s. ②Manual soldering Soldering iron temperature :270 °C, Soldering time :3s. No strength on contact.	No deformation of case of excessive looseness of the terminals.	O	—
Solderability	Soldering temperature: 245 °C Duration of immersion :soldering, for 5 sec.	New uniform coating of solder shall cover minimum of 95 % of the surface Being immersed.	O	—

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CODE NO.(OLD) CL	DRAWING NO. ELC4-632587	CODE NO. CL 6652-0062-6-800		2/2